

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT3311323

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
DAMIEN LAMBERT	03/25/2015
JOHN SPANN	03/31/2015
STEPHEN KRASULICK	03/30/2015
RECEIVING PARTY DATA	
Name:	SKORPIOS TECHNOLOGIES, INC.
Street Address:	5600 EUBANK BOULEVARD NE
Internal Address:	SUITE 200
City:	ALBUQUERQUE
State/Country:	NEW MEXICO
Postal Code:	87111
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14562169
CORRESPONDENCE DATA	
Fax Number:	(303)571-4321
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	303-571-4000
Email:	kheil@kilpatricktownsend.com
Correspondent Name:	KILPATRICK TOWNSEND & STOCKTON LLP
Address Line 1:	TWO EMBARCADERO CENTER
Address Line 2:	EIGHTH FLOOR
Address Line 4:	SAN FRANCISCO, CALIFORNIA 94111-3834
ATTORNEY DOCKET NUMBER:	92970-918729 (003910US)
NAME OF SUBMITTER:	MATTHEW B. CROOKSTON
SIGNATURE:	/Matthew B. Crookston/
DATE SIGNED:	04/15/2015
Total Attachments: 6	
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ASSIGNMENT
(Patent Application)

I, Damien Lambert, the undersigned, have invented certain inventions and improvements disclosed in a patent application entitled

**“SEMICONDUCTOR BONDING WITH COMPLIANT RESIN AND UTILIZING
HYDROGEN IMPLANTATION FOR TRANSFER-WAFER REMOVAL,”**

the specification of which is provided with this Assignment and identified by the Attorney Docket No. above. (Application No. 14/562,169 filed on December 5, 2014).

I: For good and valuable consideration, the receipt and sufficiency of which I acknowledge,

1. Agree to assign, transfer, convey, and sell, hereby assign, transfer, convey, and sell and have assigned, transferred, conveyed, and sold to Skorpis Technologies, Inc., a corporation of the State of Delaware having a principal place of business at 5600 Eubank Boulevard NE, Suite 200, Albuquerque, New Mexico 87111 (“Assignee”), the entire right, title, and interest in and to:

- (a) all intellectual property (including, without limitation, any innovation, information, invention, discovery, product, process, work or design) disclosed, embodied, shown, or claimed in the above-referenced patent application, implicitly or explicitly;
- (b) the above-referenced patent application, the right to claim priority to the above-referenced patent application, all applications based in whole or in part upon the above-referenced patent application, including, without limitation, all applications that are a provisional, non-provisional, design, divisional, continuation, continuation-in-part, registration, utility model, industrial design, reissue, renewal, substitute, extension, reexamination, post-grant review, inter partes review, supplemental examination or non-U.S. patent application or application for other rights based in whole or in part on the above-referenced patent application;
- (c) all patents (including, without limitation, all U.S. and non-U.S. patents, registrations, utility models, industrial designs, design patents, counterparts, continuations, continuations-in-part, divisionals, reissues, renewals, substitutes, extensions, reexaminations, post-grant reviews, inter partes reviews and supplemental examinations) that are granted or issued upon, or that claim priority to, any and all applications described in (b) of this paragraph or that disclose or claim intellectual property described in (a) of this paragraph, in whole or in part; and

ASSIGNMENT

U.S. Application No. 14/562,169

SEMICONDUCTOR BONDING WITH COMPLIANT RESIN AND UTILIZING
HYDROGEN IMPLANTATION FOR TRANSFER-WAFER REMOVAL


Attorney Docket No. 92970-918729 (003910US)

Page 2 of 2

- (d) all claims for damages by reason of past infringement of any rights under the applications or patents described in (a), (b) or (c) of this paragraph (including provisional rights to reasonable royalties pursuant to 35 U.S.C. § 154(d)) and the right to sue for and collect such damages and royalties for Assignee's own use.
2. Authorize and request the U.S. Patent and Trademark Office or any other U.S. or non-U.S. agency to issue to the Assignee any and all patent(s), or other rights or documents, resulting from the intellectual property, patent application(s) and patents described in paragraph 1 of this Assignment.
3. Agree to sign all papers and documents, including without limitation, applications, declarations, oaths and petitions, and, at the Assignee's expense, perform any other acts that are necessary in connection with prosecution of patent application(s) or intellectual property described in paragraph 1 of this Assignment and the enforcement of patent(s) or other rights resulting from such patent application(s) or intellectual property.
4. Agree that the terms, covenants, and conditions of this Assignment shall inure to the benefit of the Assignee, its successors, assigns and other legal representative, and shall be binding upon me, as well as my heirs, legal representatives, and assigns.
5. Promise and affirm that I have not entered, and will not enter, into any assignment, contract, or understanding that conflicts with this Assignment.

Signed on the dates indicated beside my signature.

Signature:


Damien Lambert

Date: 03/25/2015

ASSIGNMENT
(Patent Application)

I, John Spann, the undersigned, have invented certain inventions and improvements disclosed in a patent application entitled

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HYDROGEN IMPLANTATION FOR TRANSFER-WAFER REMOVAL,”

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I:

1. Agree to assign, transfer, convey, and sell, hereby assign, transfer, convey, and sell and have assigned, transferred, conveyed, and sold to Skorplos Technologies, Inc., a corporation of the State of Delaware having a principal place of business at 5600 Eubank Boulevard NE, Suite 200, Albuquerque, New Mexico 87111 (“Assignee”), the entire right, title, and interest in and to:
 - (a) all intellectual property (including, without limitation, any innovation, information, invention, discovery, product, process, work or design) disclosed, embodied, shown, or claimed in the above-referenced patent application, implicitly or explicitly;
 - (b) the above-referenced patent application, the right to claim priority to the above-referenced patent application, all applications based in whole or in part upon the above-referenced patent application, including, without limitation, all applications that are a provisional, non-provisional, design, divisional, continuation, continuation-in-part, registration, utility model, industrial design, reissue, renewal, substitute, extension, reexamination, post-grant review, inter partes review, supplemental examination or non-U.S. patent application or application for other rights based in whole or in part on the above-referenced patent application;
 - (c) all patents (including, without limitation, all U.S. and non-U.S. patents, registrations, utility models, industrial designs, design patents, counterparts, continuations, continuations-in-part, divisionals, reissues, renewals, substitutes, extensions, reexaminations, post-grant reviews, inter partes reviews and supplemental examinations) that are granted or issued upon, or that claim priority to, any and all applications described in (b) of this paragraph or that disclose or claim intellectual property described in (a) of this paragraph, in whole or in part; and

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U.S. Application No. 14/562,169

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2. Authorize and request the U.S. Patent and Trademark Office or any other U.S. or non-U.S. agency to issue to the Assignee any and all patent(s), or other rights or documents, resulting from the intellectual property, patent application(s) and patents described in paragraph 1 of this Assignment.
 3. Agree to sign all papers and documents, including without limitation, applications, declarations, oaths and petitions, and, at the Assignee's expense, perform any other acts that are necessary in connection with prosecution of patent application(s) or intellectual property described in paragraph 1 of this Assignment and the enforcement of patent(s) or other rights resulting from such patent application(s) or intellectual property.
 4. Agree that the terms, covenants, and conditions of this Assignment shall inure to the benefit of the Assignee, its successors, assigns and other legal representative, and shall be binding upon me, as well as my heirs, legal representatives, and assigns.
 5. Promise and affirm that I have not entered, and will not enter, into any assignment, contract, or understanding that conflicts with this Assignment.

Signed on the dates indicated beside my signature.

Signature: _____

John Spann

Date: _____

3/3/15

ASSIGNMENT
(Patent Application)

I, Stephen Krasulick, the undersigned, have invented certain inventions and improvements disclosed in a patent application entitled

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 - (a) all intellectual property (including, without limitation, any innovation, information, invention, discovery, product, process, work or design) disclosed, embodied, shown, or claimed in the above-referenced patent application, implicitly or explicitly;
 - (b) the above-referenced patent application, the right to claim priority to the above-referenced patent application, all applications based in whole or in part upon the above-referenced patent application, including, without limitation, all applications that are a provisional, non-provisional, design, divisional, continuation, continuation-in-part, registration, utility model, industrial design, reissue, renewal, substitute, extension, reexamination, post-grant review, inter partes review, supplemental examination or non-U.S. patent application or application for other rights based in whole or in part on the above-referenced patent application;
 - (c) all patents (including, without limitation, all U.S. and non-U.S. patents, registrations, utility models, industrial designs, design patents, counterparts, continuations, continuations-in-part, divisionals, reissues, renewals, substitutes, extensions, reexaminations, post-grant reviews, inter partes reviews and supplemental examinations) that are granted or issued upon, or that claim priority to, any and all applications described in (b) of this paragraph or that disclose or claim intellectual property described in (a) of this paragraph, in whole or in part; and

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3. Agree to sign all papers and documents, including without limitation, applications, declarations, oaths and petitions, and, at the Assignee's expense, perform any other acts that are necessary in connection with prosecution of patent application(s) or intellectual property described in paragraph 1 of this Assignment and the enforcement of patent(s) or other rights resulting from such patent application(s) or intellectual property.
4. Agree that the terms, covenants, and conditions of this Assignment shall inure to the benefit of the Assignee, its successors, assigns and other legal representative, and shall be binding upon me, as well as my heirs, legal representatives, and assigns.
5. Promise and affirm that I have not entered, and will not enter, into any assignment, contract, or understanding that conflicts with this Assignment.

Signed on the dates indicated beside my signature.

Signature: _____

Stephen Krasulick

Date: _____

3-30-15

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